

1.6X0.8mm SMD CHIP LED LAMP (0.25mm Height)

Part Number: APG1608SURKC/T

Hyper Red

Features

- 1.6mmX0.8mm SMT LED, 0.25mm thickness.
- Low power consumption.
- Wide viewing angle.
- Compatible with automatic placement equipment.
- Ideal for backlight and indicator.
- Package: 2000pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

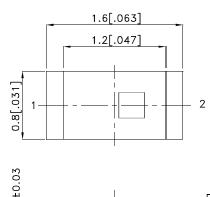
Description

The Hyper Red source color devices are made with Al-GaInP on GaAs substrate Light Emitting Diode.

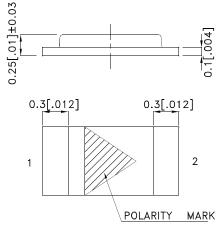
Applications

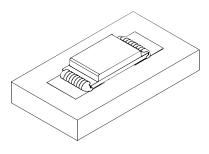
- 1. Mobile phone Keypad indicator and backlight.
- 2.Flat backlight for LCD, switch and symbol.
- 3.Toys.

Package Dimensions









- 1. All dimensions are in millimeters (inches)
- 2. Tolerance is ±0.1(0.004") unless otherwise noted.
- 3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice 4. The device has a single mounting surface. The device must be mounted according to the specifications.

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Selection Guide

Part No.	Part No. Dice Lens Type		lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,,	Min.	Тур.	201/2
APG1608SURKC/T	Hyper Red (AlGaInP)	Water Clear	200	350	120°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red	650		nm	IF=20mA
λD [1]	Dominant Wavelength	Hyper Red	630		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Hyper Red	20		nm	IF=20mA
С	Capacitance	Hyper Red	35		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Hyper Red	2	2.5	V	IF=20mA
lR	Reverse Current	Hyper Red		10	uA	V _R =5V

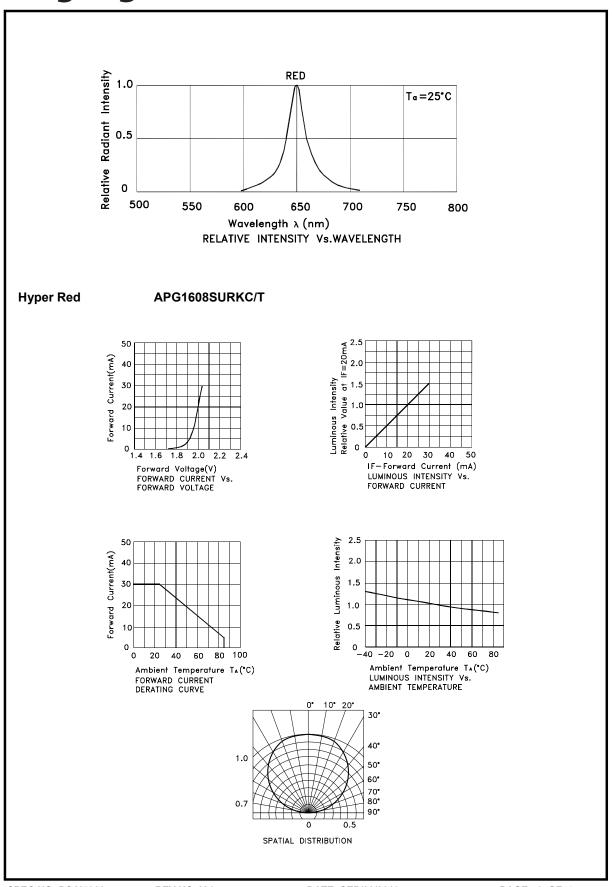
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

Parameter	Hyper Red	Units	
Power dissipation	75	mW	
DC Forward Current	30	mA	
Peak Forward Current [1]	150	mA	
Reverse Voltage	5	V	
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

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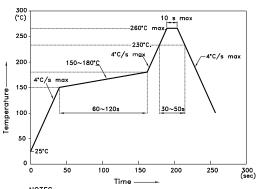
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Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

3.Number of reflow process shall be 2 times or less.

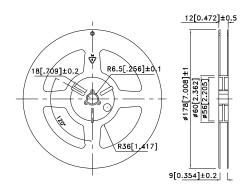
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)

0.8

0.8

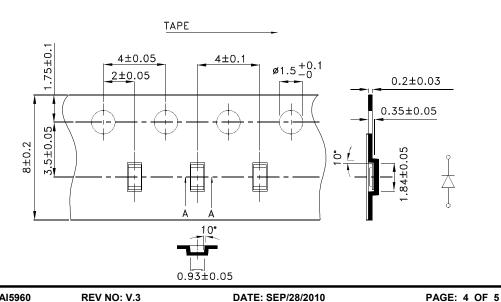
0.85

Reel Dimension



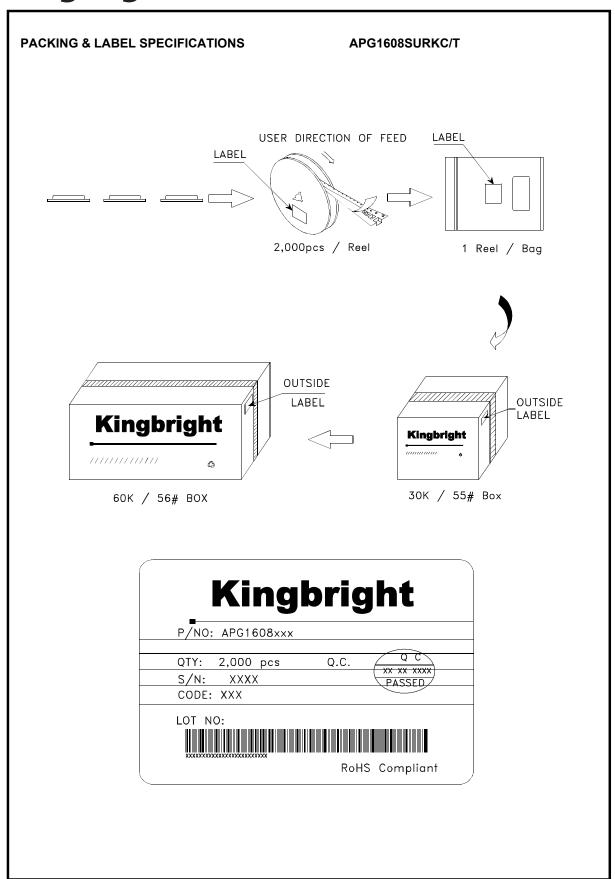
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Tape Dimensions (Units: mm)



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0.8



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